



Product Change Notification

104589 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 104589 - 00
Change Title: 32Mb Advanced + Boot Block Flash with 4 Mb SRAM, PCN 104589-00, FFF, Change from .15 μ m and .12 μ m & adding additional source 4Mb SRAM
Date of Publication: November 22, 2004

Type of Change Notification:
FFF - (Form-Fit-Function)

Key Characteristics of the Change:
Product Material

Forecasted Key Milestones:

Date of Samples Availability:	Dec 22, 2004
Date of Qualification Data Availability:	Feb 11, 2005
Date Customer Must be Ready to Receive Post-Conversion Material:	Feb 23, 2005

Description of Change to the Customer:

Intel will begin assembling 32/4 C3 stacked devices with .12 μ m SRAM. Prior production material had been assembled with a .15 μ m SRAM. In addition, Intel is adding an additional qualified source of 4Mb SRAM and will begin assembling with both sources in our 32/4 C3 stacked device.

Both of the new SRAM's will have the same functional specifications as the existing SRAM device. There is no change to the datasheet of the 32/4 C3 stacked device. The 'Products Affected' table below gives the part numbers for the 32/4 C3 devices. Intel will not be modifying the part number.

Intel will fully qualify these new SRAM's and the new stack devices will meet Intel's stringent quality and reliability standards.

This will improve supply flexibility to better serve the customers taking this device.

Customer Impact of Change and Recommended Action:

Intel does not anticipate any impact to customer's applications. This SRAM lithography change meets Intel's quality and reliability standards and is backwards compatible with Intel's current stacked chip scale package.

Intel will not be modifying the part numbers. The 'Products Affected' table below lists the current part numbers for the 32/4 C3 stacked

devices. Product may be shipped interchangeably after the Key Milestone dates listed above. Customers must be positioned to accept and use the 32/4 C3 product from either source based on the Key Milestone Dates noted above.

Products Affected / Intel Ordering Codes:

Component Product Table

Product Code	Spec/ROM	MM#
PF38F1010C0ZBL0862197		862197
PF38F1010C0ZBL0S B48	S B48	862192
PF38F1010C0ZBL0S B93	S B93	862180
PF38F1010C0ZTL0862191		862191
PF38F1010C0ZTL0S B48	S B48	862194
PF38F1010C0ZTL0S B93	S B93	862193
RD38F1010C0ZBL0851208		851208
RD38F1010C0ZBL0S B48	S B48	851203
RD38F1010C0ZBL0S B93	S B93	849851
RD38F1010C0ZBL0S L78L	S L78L	856560
RD38F1010C0ZTL0849849		849849
RD38F1010C0ZTL0S B48	S B48	851207
RD38F1010C0ZTL0S B93	S B93	849850
RD38F1010C0ZTL0S L7MC	S L7MC	862052

Sample Operating Code

Sample Product Code	Sample Spec/ROM	Sample MM#	Description
PF38F1010C0ZBL0Q CN8	Q CN8	868794	32/4 C3 w/ .12µm SRAM
PF38F1010C0ZTL0Q CN5	Q CN5	868792	32/4 C3 w/ .12µm SRAM
RD38F1010C0ZBL0Q BD4	Q BD4	864709	32/4 C3 w/ Additional source
RD38F1010C0ZTL0Q BD1	Q BD1	864704	32/4 C3 w/ Additional source

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

November 22, 2004

Revision Number:

00

Reason:

Originally Published PCN